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17334

**PATENT APPLICATION**  
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q62228

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. Musser

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND  
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND  
THE LIKE

**PETITION FOR EXTENSION OF TIME UNDER 37 C.F.R. § 1.136**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 C.F.R. § 1.136, Applicant hereby petitions for an extension of time of one month(s), extending the time for responding to the Office Action of November 23, 2004 to March 23, 2005.

A check for the statutory fee of \$120.00 is attached. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this sheet is enclosed.

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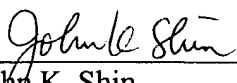
WASHINGTON OFFICE

**23373**

CUSTOMER NUMBER

Date: March 16, 2005

Respectfully submitted,

  
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John K. Shin  
Registration No. 48,409